



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

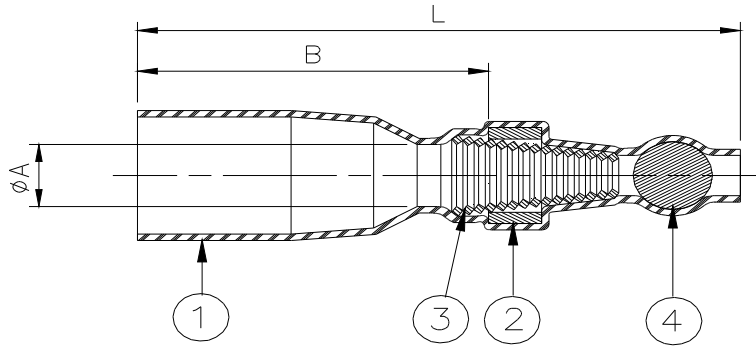
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SPECIFICATION CONTROL DRAWING



Product Revision		Ball Color	Product Dimensions			Copper Cross Section		Bundle ø	
Product Name			L±3.5 (L±0.140)	øA	øB	Min. mm ² (CMA)	Max. mm ² (CMA)	øD max	M±1 (M±0.04)
SGRP-1	C	Green	38.3 (1.510)	3.1±0.2 (0.125±0.008)	26.0±2 (1.025±0.079)	0.7 (1400)	2.4 (4800)	4.0 (0.160)	15 (0.590)
SGRP-2	C	Red	37.7 (1.485)	3.9±0.2 (0.155±0.008)	23.5±2 (0.925±0.079)	2.0 (4000)	4.0(8000)	6.0 (0.235)	15 (0.590)
SGRP-3	D	Blue	44.5 (1.750)	5.35±0.3 (0.210±0.012)	25.5±3 (1.00±0.118)	3.5 (7000)	9.0(18000)	8.5 (0.335)	15 (0.590)
SGRP-4	D	Yellow	45.5 (1.790)	7.15±0.3 (0.280±0.012)	25.0±3 (0.985±0.118)	7.5 (15000)	15.0(3000)	10.5 (0.410)	15 (0.590)

These products are tested to RB109.

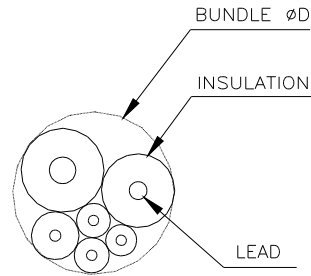
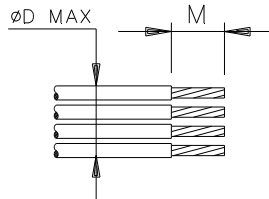
MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- SOLDER PREFORM WITH FLUX:
SOLDER: TYPE Sn60 per ANSI-J-STD-006.
FLUX: TYPE ROM1 per ANSI-J-STD-004.
- CONICAL SPRING: Square copper wire.
- END CLOSURE BALL: Tinted glass. Color: see table.


APPLICATION

- These controlled soldering devices are designed stub splicing of stranded wires with bare copper conductor having an insulation rated for 85°C minimum.
- Temperature range: class 3A, -40°C to +125°C.
Vibration range: class 1 (body).
Seal range: class 0 (seal porous or no seal).
- For installation procedure and application equipment consult, RPIP-820-00.

For best results, prepare the cable as shown:



* A trademark of TE Connectivity

		TE Connectivity 300 Constitutional Drive Menlo Park, CA 94025 USA		Raychem		TITLE: SOLDERGRIP* STUB SPLICE			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO.: SGRP-X					
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ANGLES: N/A ROUGHNESS IN MICRON		TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DATE: 15-Apr-11		DOC ISSUE: 6	
DRAWN BY: M. FORONDA		CAGE CODE: 06090		REPLACES: D981339		DCR NUMBER: D020135		PROD. REV.: SEE TABLE	
				SCALE: None		SIZE: A		SHEET: 1 of 1	

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